TLC69625-Q1 Automotive 60mA, 24-Channel LED Driver with Integrated Oscillator and Advance Diagnostics

1 Features

- AEC-Q100 qualified for automotive applications
  - Grade 1: –40°C to 125°C ambient operating temperature
  - Device HBM classification level H1C
  - Device CDM classification level C4B
- Targeted Functional Safety-Compliant
  - Developed for functional safety applications
  - Documentation available to aid ISO 26262 system design up to ASIL B
- 24 integrated current sinks
  - Programmable 16-bit PWM / Hybrid dimming
  - Programmable 7-bit analog dot correction (DC)
  - Maximum output current / voltage: 60mA / 16V
- Integrated 33MHz oscillator
  - 16-bit PWM output in 500Hz
  - >20KHz refresh rate with enhanced spectrum (ES) PWM
- High speed communication
  - Serial peripheral interface (SPI)
  - Data rates up to 17Mbps
- Power efficiency optimization
  - Adaptive headroom voltage control (AHVC)
  - Device power save mode (PSM)
- EMI mitigation
  - Interface: programmable buffer driving capability
  - Current sinks: phase shifting / spread spectrum
- Protection and Diagnostic
  - LED: open / short detection / health check
  - Current sink: adjacent-pin short / health check
  - Interface: CRC / command error / time-out error / communication watchdog
  - Device: under voltage / ISET out of range / thermal shutdown / memory CRC / OTP CRC / OSC watchdog

2 Applications

- Automotive Central Information Display
- Automotive Cluster Display
- Automotive Head-up Display

3 Description

The TLC69625-Q1 is a LED driver with 24 constant current sink channels which can provide up to 16-bit individual pixel-level LED PWM control. The additional 7-bit dot correction (DC) is also implemented to each channel to control peak current. Each device shares data stream by serial peripheral interface (SPI) which supports up to 511 devices connection. The interface is software compatible with LED drivers in the same group which can be applied to different application scenarios based on LED current and total LED number.

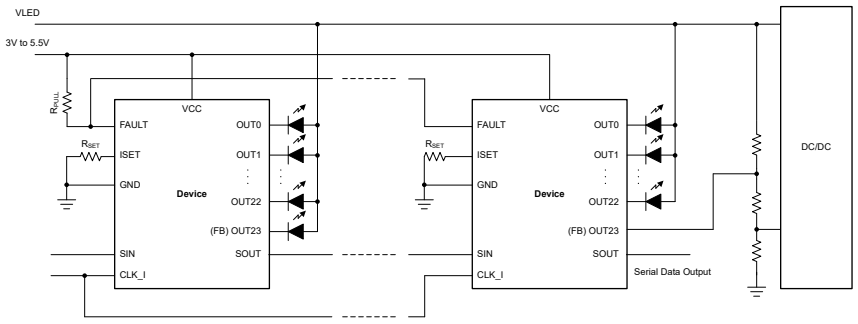
To optimize overall systematic power efficiency, the device is equipped with adaptive headroom voltage control (AHVC) scheme to optimize headroom voltage across each channel and device. Only the OUT23 pin from the last device of daisy chain is required to be programmed as FB pin to optimize LED supply voltage from DC/DC.

The TLC69625-Q1 is equipped diagnostics for LED, current sink, communication and device.

Device Information

PART NUMBER	PACKAGE(1)	PACKAGE SIZE(2)
TLC69625-Q1	WQFN (32) Wettable flank	4mm × 4mm
	HTSSOP (32)	11mm × 6.1mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.
(2) The package size (length × width) is a nominal value and includes pins, where applicable.



Simplified Schematic

An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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4 Device Comparison

PART NUMBER	CHANNEL NUMBER	MAX. CHANNEL CURRENT	FUNCTIONAL SAFETY CLASSIFICATION	INTERFACE	SOFTWARE COMPATIBLE
TLC69621-Q1	8	60mA	Functional Safety-Capable	SPI	Group 1
TLC69624-Q1	24				
TLC69627-Q1	48				
TLC69631-Q1	8	100mA			
TLC69634-Q1	24				
TLC69637-Q1	48				
TLC69622-Q1	8	60mA	Functional Safety-Compliant	SPI	Group 2
TLC69625-Q1	24				
TLC69628-Q1	48				
TLC69632-Q1	8	100mA			
TLC69635-Q1	24				
TLC69638-Q1	48				
TLC69623-Q1	8	60mA	Functional Safety-Compliant	CSI	Group 3
TLC69626-Q1	24				
TLC69629-Q1	48				
TLC69633-Q1	8	100mA			
TLC69636-Q1	24				
TLC69639-Q1	48				

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5 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

5.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

5.2 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

5.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.
All trademarks are the property of their respective owners.

5.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

5.5 Glossary

TI Glossary	This glossary lists and explains terms, acronyms, and definitions.

6 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
July 2026	*	Initial Release

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7 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGE OPTION ADDENDUM

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/Ball material (4)	MSL rating/Peak reflow (5)	Op temp (°C)	Part marking (6)
TLC69625QDAPRQ1	Active	Production	HTSSOP (DAP) | 32	2500 | LARGE T&R	Yes	NIPDAU	Level-2-260C-168 HR	-40 to 125	TLC69625Q1
TLC69625QRSNRQ1	Active	Production	WQFN (RSN) | 32	5000 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	69625Q1

(1) **Status:** For more details on status, see our product life cycle.
(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.
(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.
(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

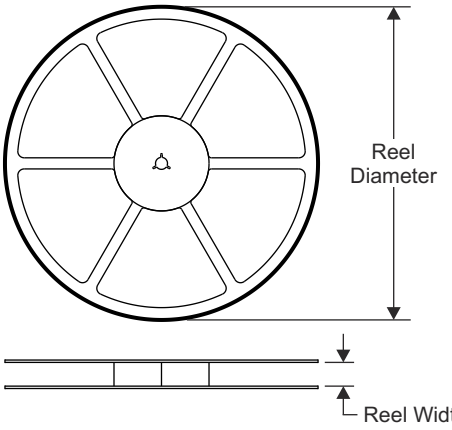
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

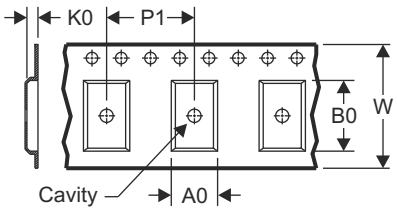
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7.1 Tape and Reel Information

REEL DIMENSIONS

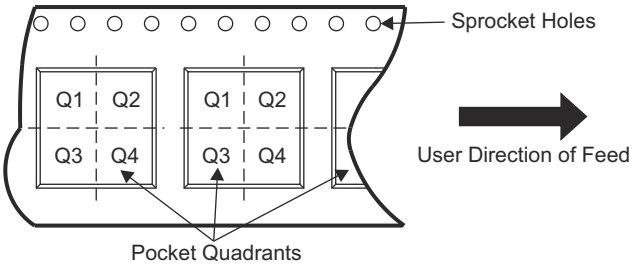


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

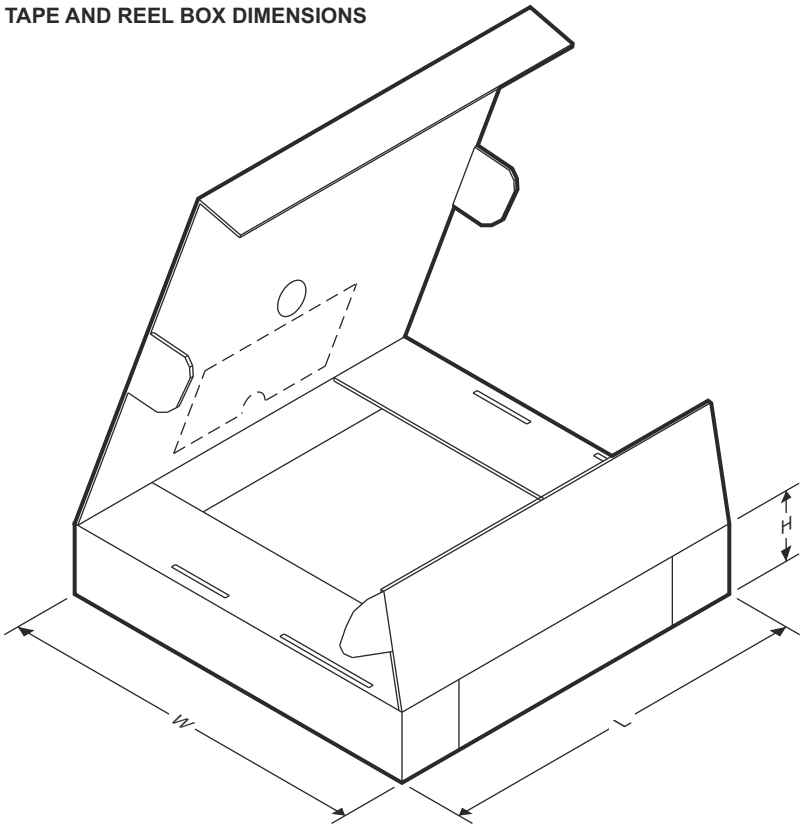
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC69625QDAPRQ1	HTSSOP	DAP	32	2500	330	24.4	8.8	11.8	1.8	12	24	Q1
TLC69625QRSNRQ1	WQFN	RSN	32	5000	330	12.4	4.25	4.25	1.15	8	12	Q2

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TAPE AND REEL BOX DIMENSIONS

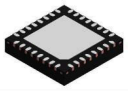


Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC69625QDAPRQ1	HTSSOP	DAP	32	2500	356	356	45
TLC69625QRSNRQ1	WQFN	RSN	32	5000	367	367	35

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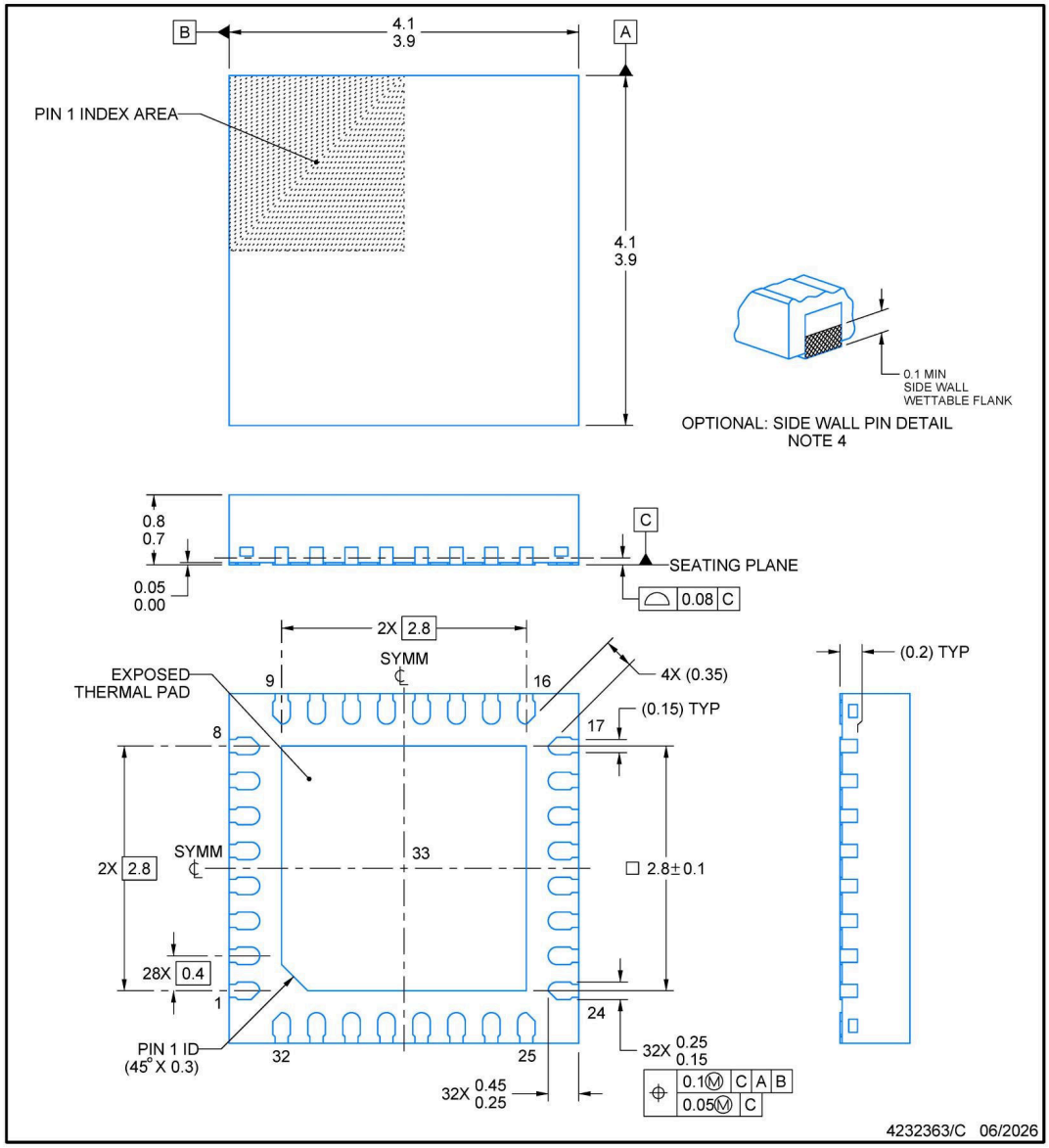
PACKAGE OUTLINE

RSN0032D



WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES:

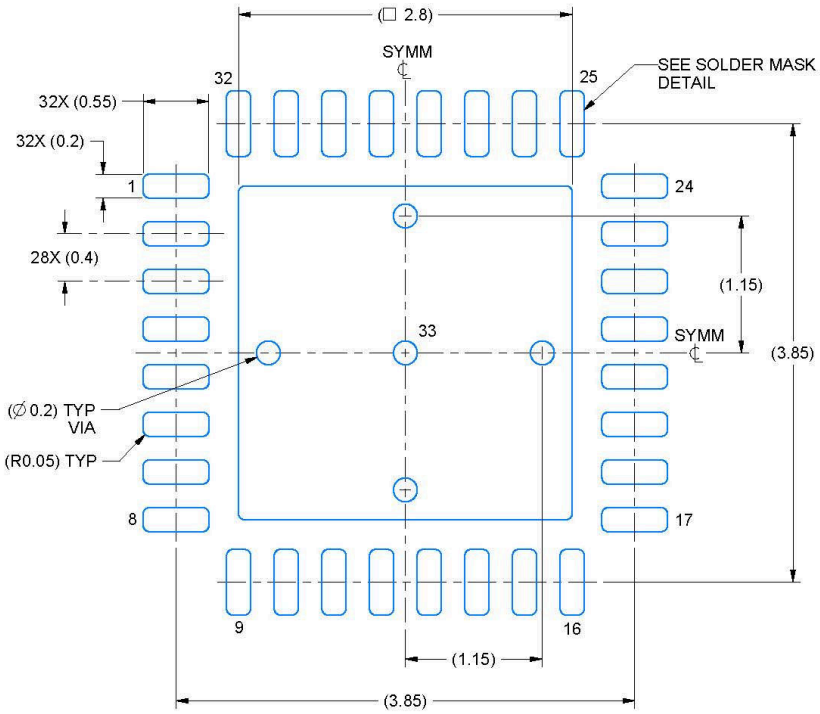
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.
4. Minimum 0.1 mm solder wetting on pin side wall. Available for wettable flank version only.

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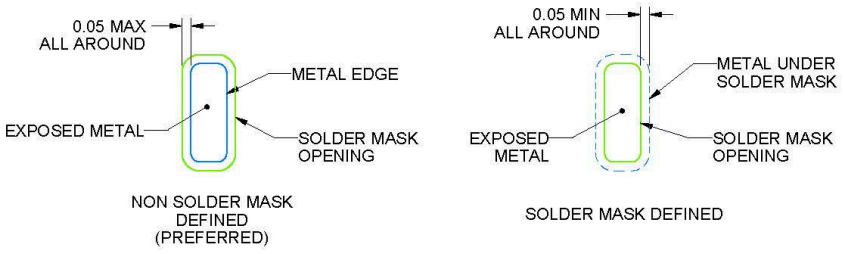
EXAMPLE BOARD LAYOUT

RSN0032D — **WQFN - 0.8 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X



SOLDER MASK DETAILS

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NOTES: (continued)

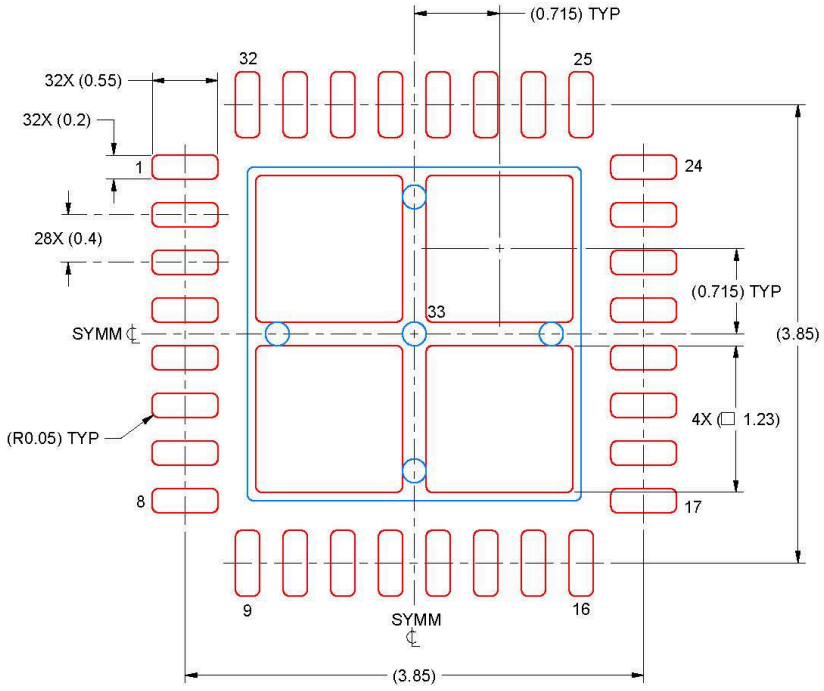
5. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
6. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

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EXAMPLE STENCIL DESIGN

RSN0032D — **WQFN - 0.8 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.1 MM THICK STENCIL
SCALE: 20X

EXPOSED PAD 33
77% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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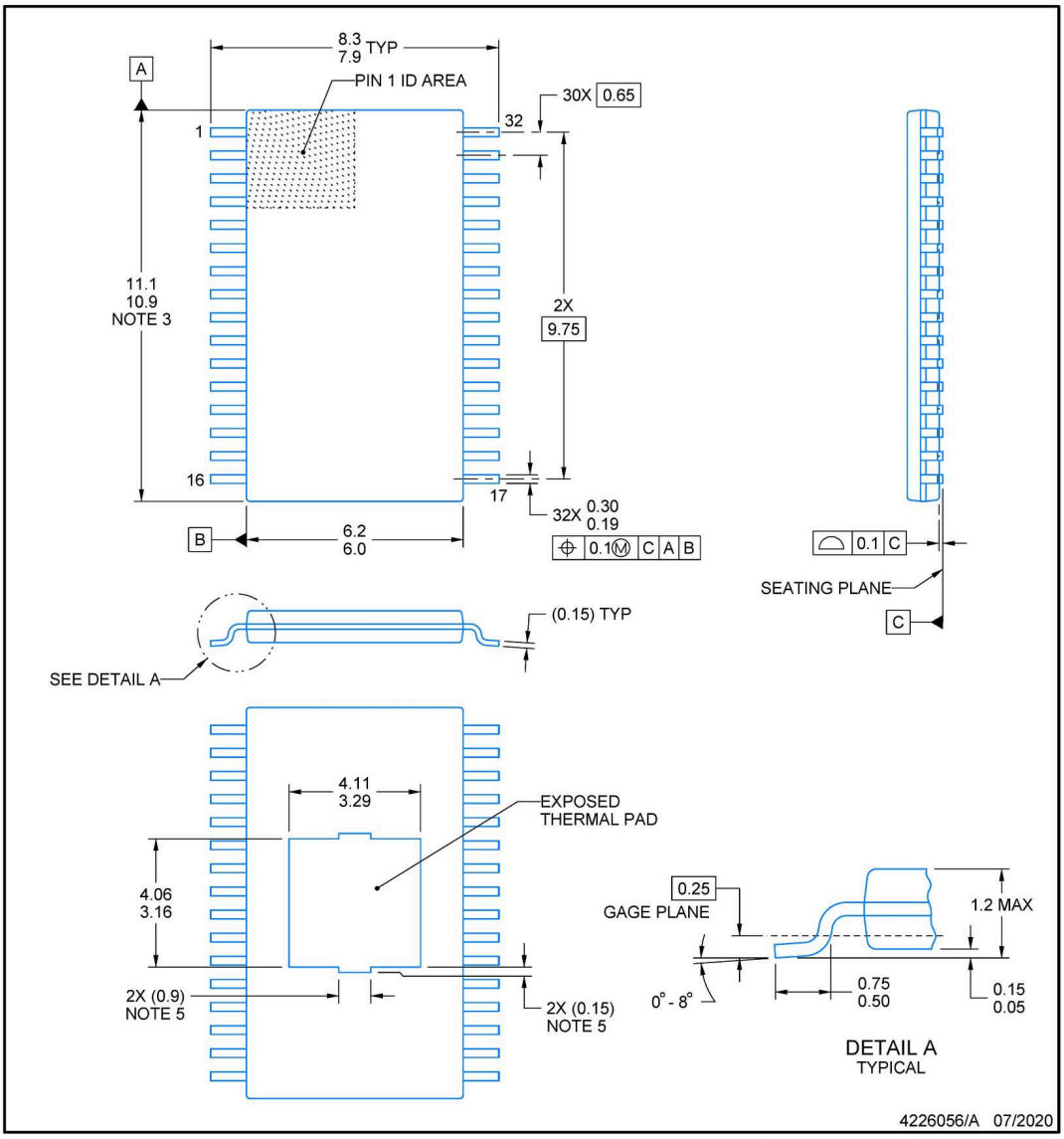


PACKAGE OUTLINE

DAP0032F

PowerPAD™ TSSOP - 1.2 mm max height

PLASTIC SMALL OUTLINE



PowerPAD is a trademark of Texas Instruments.

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.
5. Features may differ and may not be present.

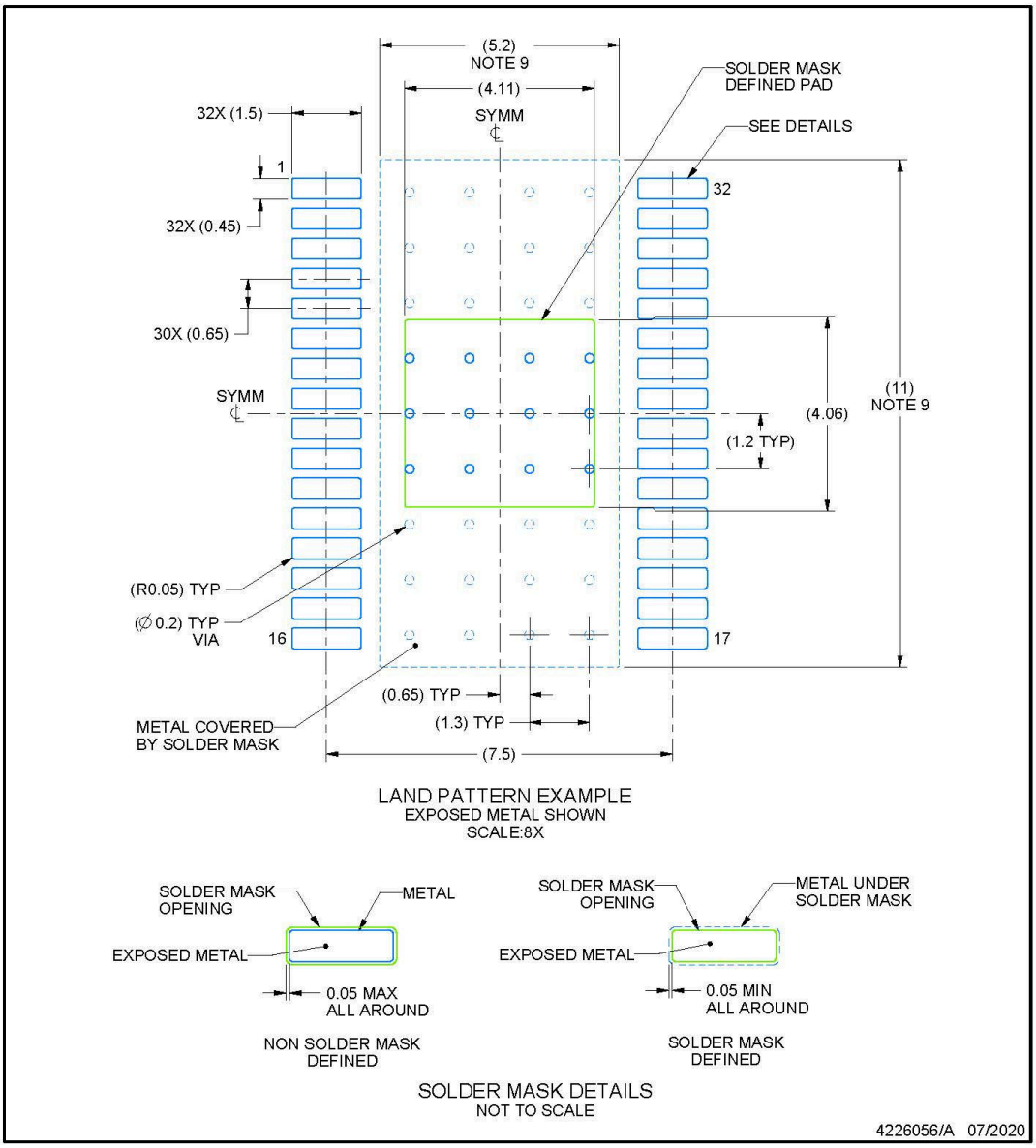
TEXAS INSTRUMENTS
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EXAMPLE BOARD LAYOUT

DAP0032F — **PowerPAD™ TSSOP - 1.2 mm max height**

PLASTIC SMALL OUTLINE



NOTES: (continued)

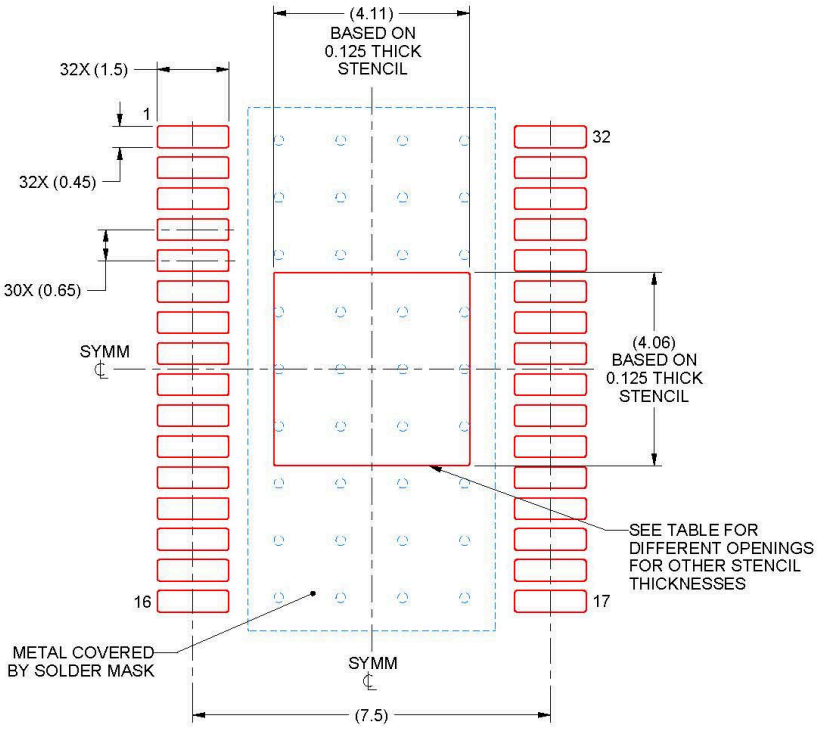
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.

www.ti.com

EXAMPLE STENCIL DESIGN

DAP0032F — **PowerPAD™ TSSOP - 1.2 mm max height**

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE
EXPOSED PAD
100% PRINTED SOLDER COVERAGE BY AREA
SCALE:8X

STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	4.60 X 4.54
0.125	4.11 X 4.06 (SHOWN)
0.15	3.75 X 3.71
0.175	3.47 X 3.43

4226056/A 07/2020

NOTES: (continued)

10. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
11. Board assembly site may have different recommendations for stencil design.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TLC69625QDAPRQ1	Active	Production	HTSSOP (DAP) | 32	2500 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-	TLC69625Q1
TLC69625QRSNRQ1	Active	Production	QFN (RSN) | 32	5000 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-	69625Q1

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

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Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

GENERIC PACKAGE VIEW

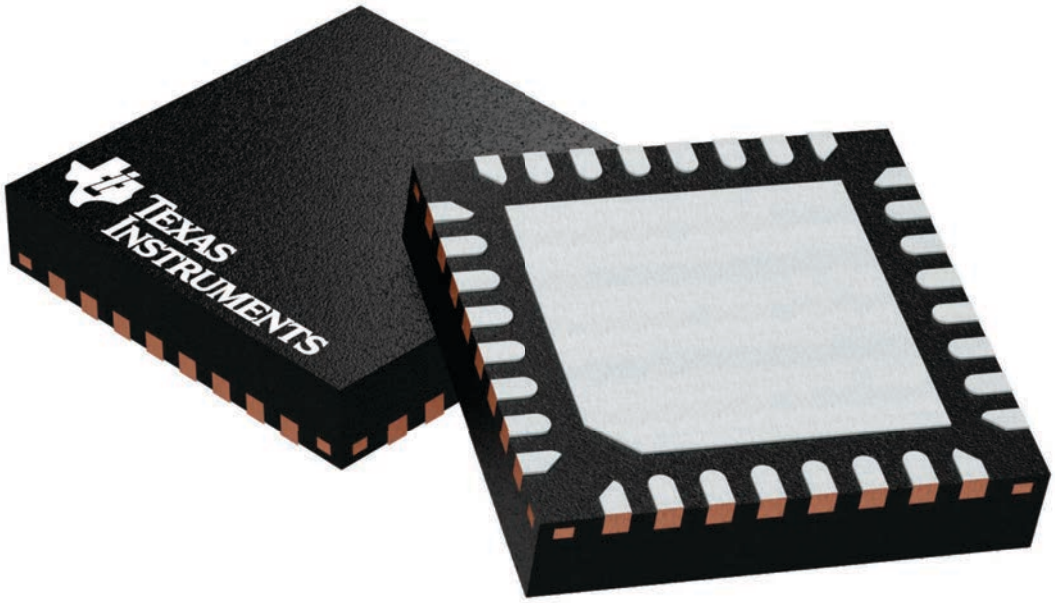
RSN 32

WQFN - 0.8 mm max height

4 x 4, 0.4 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



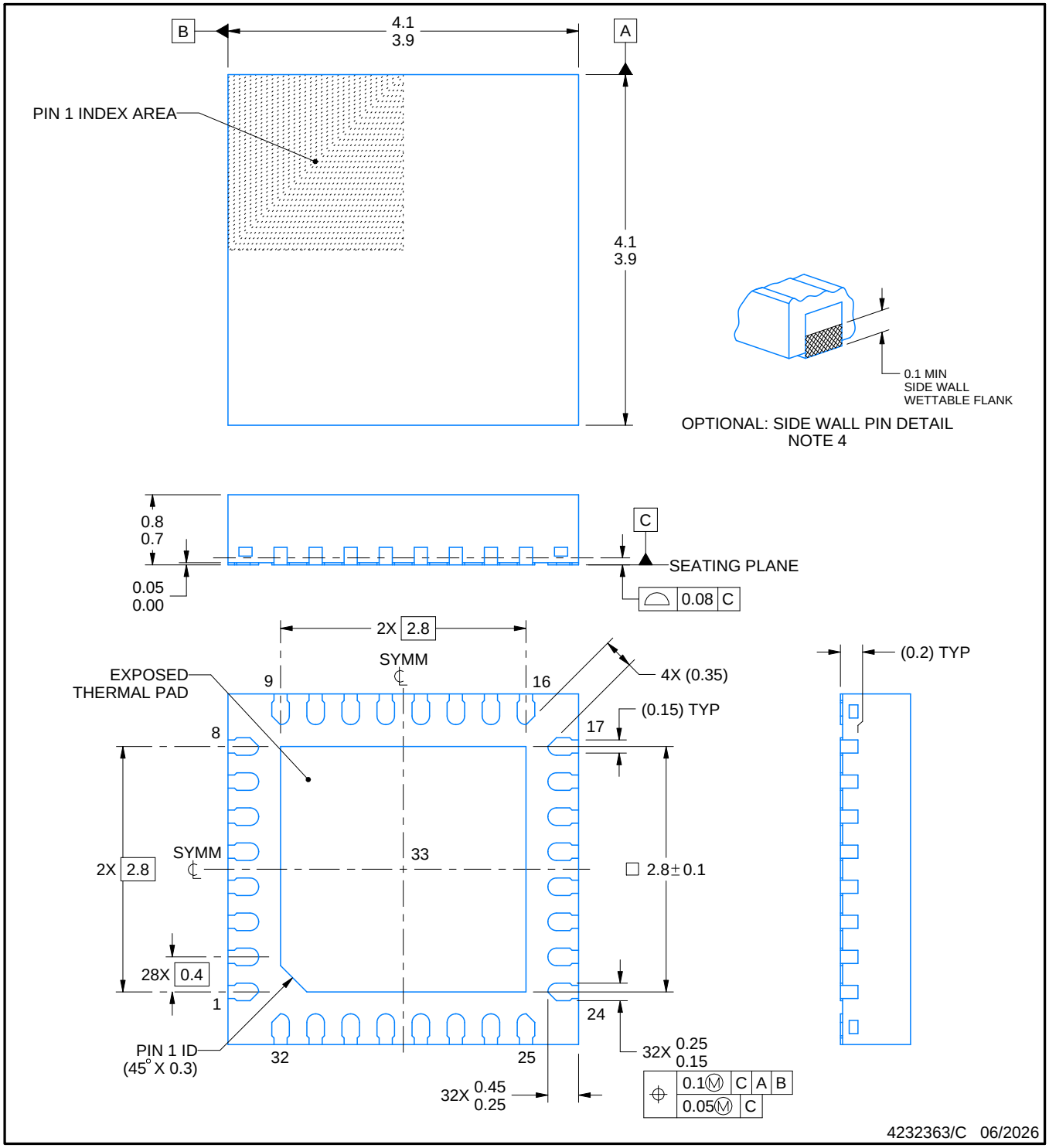
4225265/A

PACKAGE OUTLINE

RSN0032D

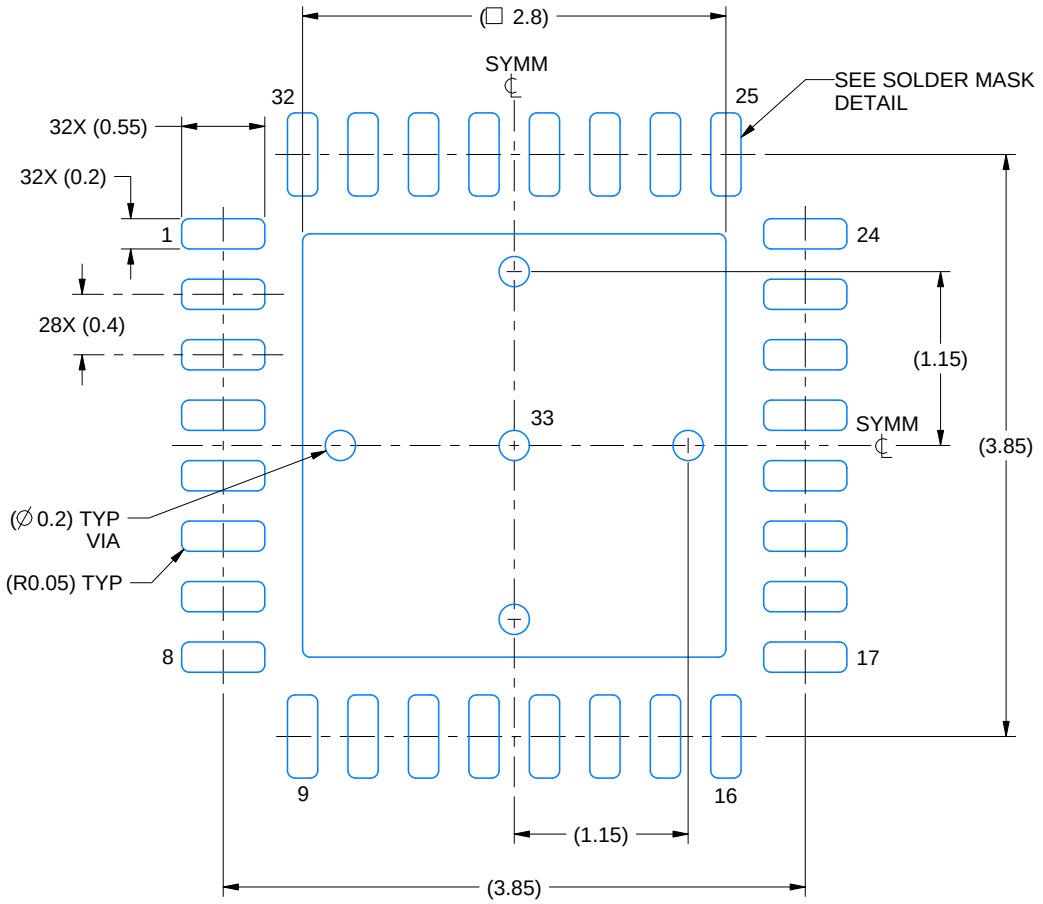
WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

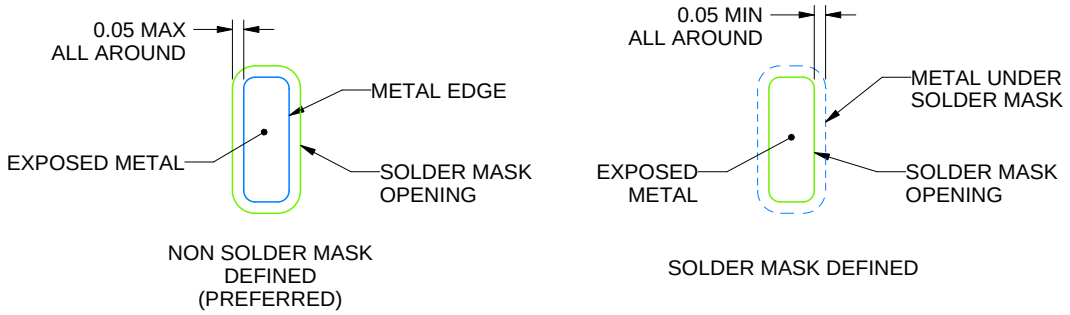


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.
4. Minimum 0.1 mm solder wetting on pin side wall. Available for wettable flank version only.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X



SOLDER MASK DETAILS

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NOTES: (continued)

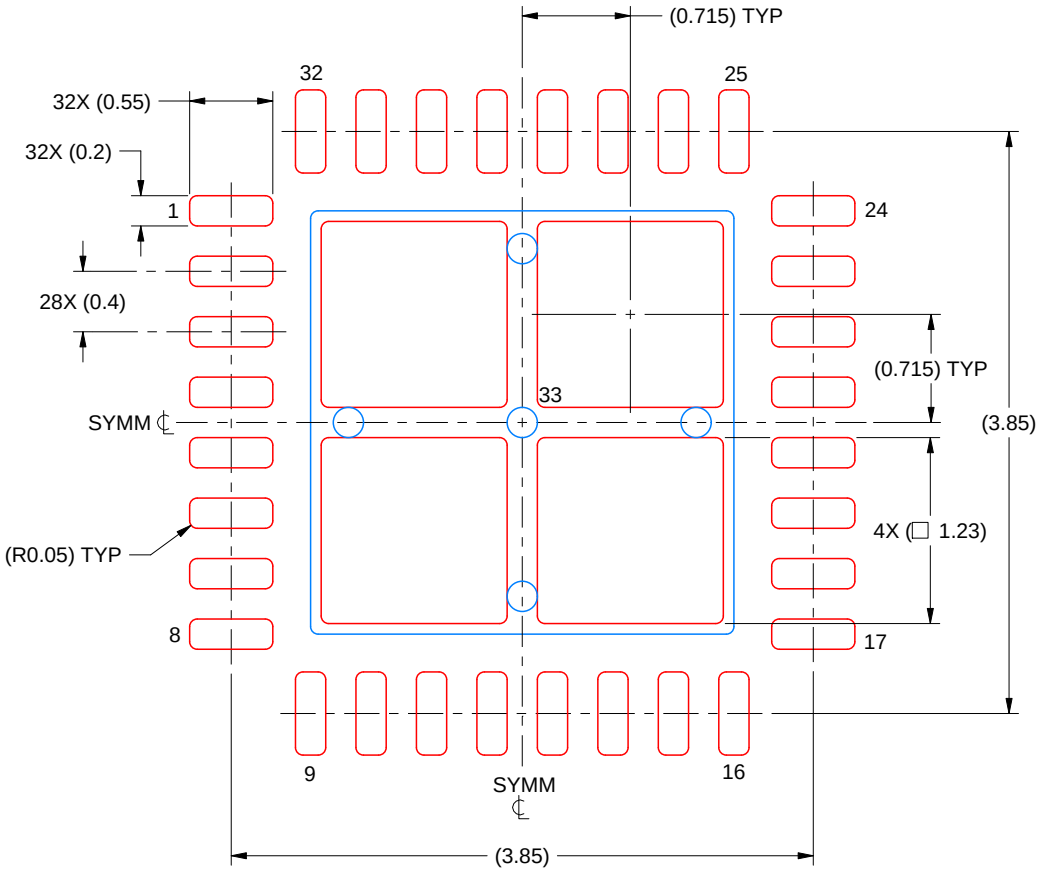
5. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
6. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

RSN0032D

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.1 MM THICK STENCIL
SCALE: 20X

EXPOSED PAD 33
77% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

4232363/C 06/2026

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

GENERIC PACKAGE VIEW

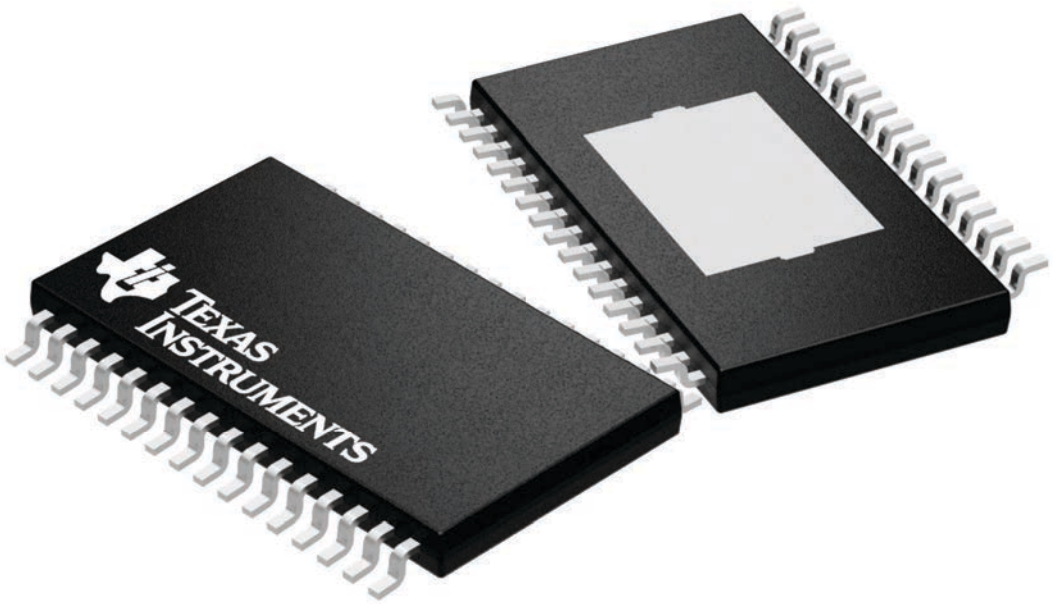
DAP 32

PowerPAD™ TSSOP - 1.2 mm max height

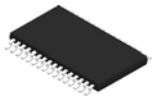
8.1 x 11, 0.65 mm pitch

PLASTIC SMALL OUTLINE

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4225303/A

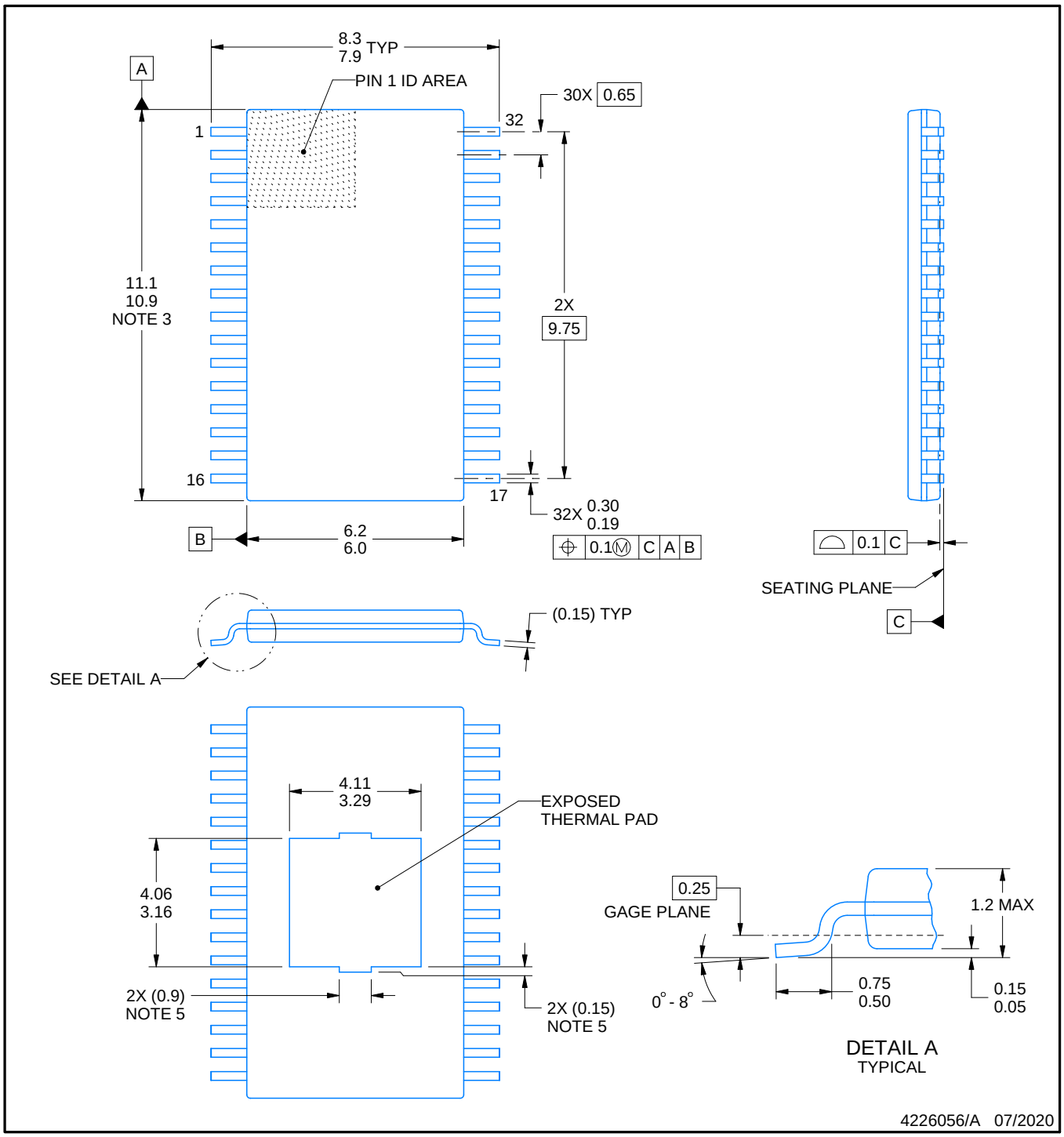


PACKAGE OUTLINE

DAP0032F

PowerPAD™ TSSOP - 1.2 mm max height

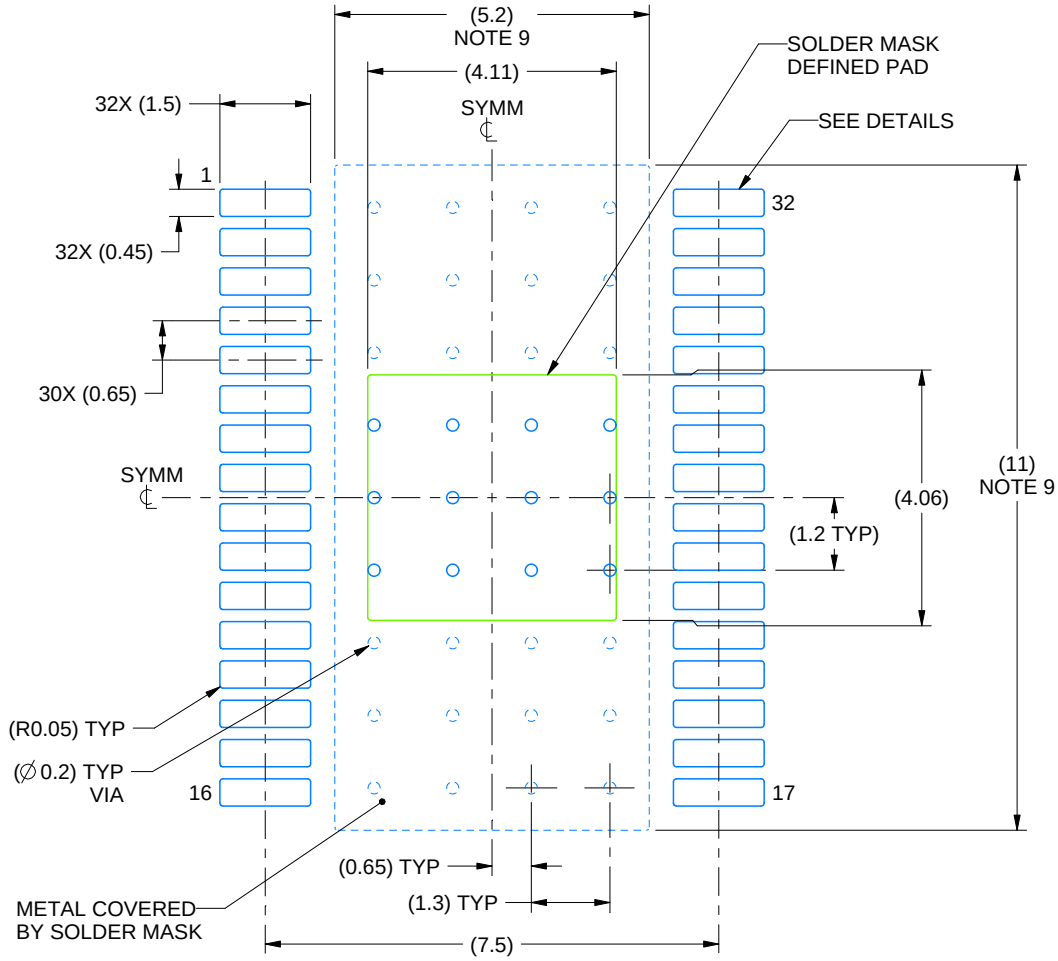
PLASTIC SMALL OUTLINE



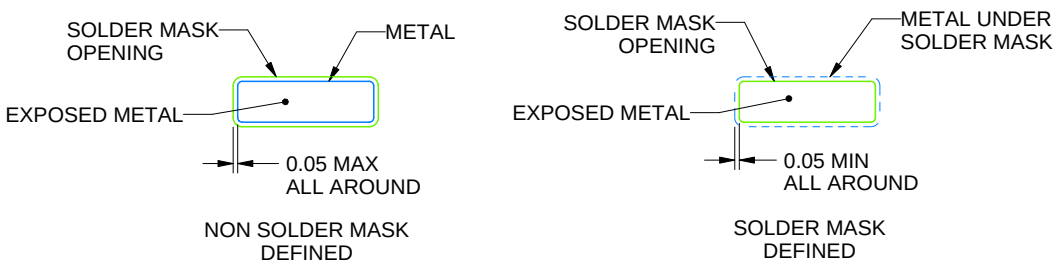
PowerPAD is a trademark of Texas Instruments.

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.
5. Features may differ and may not be present.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X

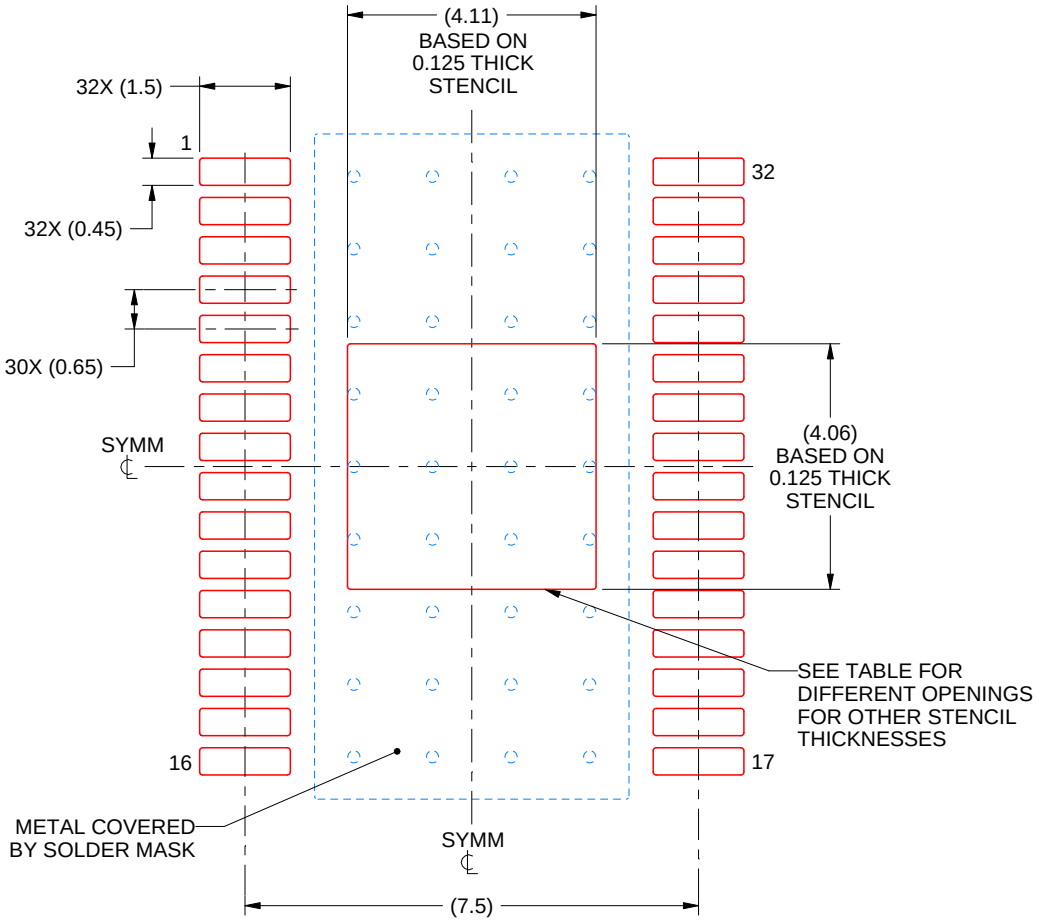


SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.



SOLDER PASTE EXAMPLE
EXPOSED PAD
100% PRINTED SOLDER COVERAGE BY AREA
SCALE:8X

STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	4.60 X 4.54
0.125	4.11 X 4.06 (SHOWN)
0.15	3.75 X 3.71
0.175	3.47 X 3.43

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NOTES: (continued)

10. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
11. Board assembly site may have different recommendations for stencil design.

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